



#### 30V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
201/	9mΩ @ V <sub>GS</sub> = 10V	12A
30V	13.5mΩ @ $V_{GS} = 4.5V$	10A

### **Features**

- 0.4mm Profile—Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

## **Description**

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

# **Applications**

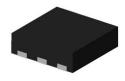
- · General Purpose Interfacing Switch
- Power Management Functions

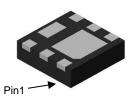
### \_\_\_

Case: X2-DFN2020-6

**Mechanical Data** 

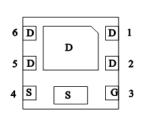
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.006 grams (Approximate)



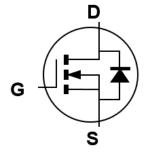


Top View Bottom View

X2-DFN2020-6 (Type W)







**Equivalent Circuit** 

## **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMT35M4LFDF4-7	X2-DFN2020-6 (Type W)	3,000/Tape & Reel
DMT35M4LFDF4-13	X2-DFN2020-6 (Type W)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

Site 1



XT = Product Type Marking Code YM = Date Code Marking Y = Year (ex: I = 2021) M = Month (ex: 9 = September)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н	ı	J	K	L	М	N	0	Р	R	S	Т
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



XT = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 1 = 2021) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	0	1	2	3	4	5	6	7	8	9	0	1

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	X	Υ	Z



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			VDSS	30	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current Vac. 40V (Note 6)	Steady	T <sub>A</sub> = +25°C	l-	12	^
Continuous Drain Current, Vos = 10V (Note 6)	State	T <sub>A</sub> = +70°C	ID	10	A
Maximum Body Diode Forward Current			Is	3	Α
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	6)		I <sub>DM</sub>	80	Α
Pulsed Drain Body Diode Forward Current (380µs P	sed Drain Body Diode Forward Current (380µs Pulse, Duty Cycle = 1%)		lsм	80	Α
Avalanche Current (L = 0.1mH) (Note 8)	I <sub>AS</sub>	22	Α		
Avalanche Energy (L = 0.1mH) (Note 8)			Eas	25	mJ

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.91	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	138	°C/W
Total Power Dissipation (Note 6)		PD	2.19	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	57	°C/W
Thermal Resistance, Junction to Case (Note 7)		R <sub>θ</sub> JC	9.6	C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

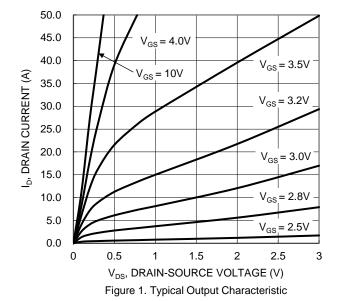
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

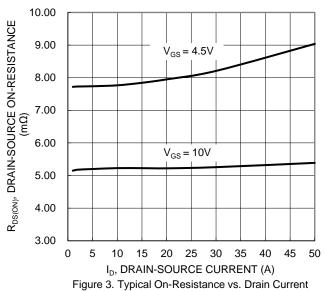
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BVDSS	30			V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.15	_	2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	D-s/s/		6	9	mΩ	$V_{GS} = 10V, I_{D} = 20A$
Static Dialif-Source Off-Resistance	R <sub>DS(ON)</sub>	_	8	13.5	11122	$V_{GS} = 4.5V, I_D = 15A$
Diode Forward Voltage	VsD	_	0.7	1	V	$V_{GS} = 0V$ , $I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C <sub>iss</sub>	_	1009			15)()(
Output Capacitance	Coss	_	925		pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	50	_		I = 1.0WI IZ
Gate Resistance	Rg	_	2	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$
Total Gate Charge (VGS = 4.5V)	Qg	_	8.1	_		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	14.9	_	nC	\/ 45\/ I- 0A
Gate-Source Charge	Qgs	_	2.3	_	iiC	$V_{DD} = 15V$ , $I_D = 9A$
Gate-Drain Charge	$Q_{gd}$	_	3.4	_		
Turn-On Delay Time	td(on)	_	3.6	_		
Turn-On Rise Time	t <sub>R</sub>	_	4.4	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	15	_	ris	$R_g = 3\Omega$ , $I_D = 9A$
Turn-Off Fall Time	tF	_	6.9	_		
Reverse Recovery Time	t <sub>RR</sub>	_	29.4	_	ns	L 1 5 \ di/dt 100 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Reverse Recovery Charge	QRR	_	19.2	_	nC	I <sub>F</sub> = 1.5A, di/dt = 100A/μs

5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
  7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.







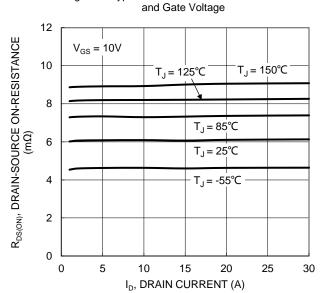
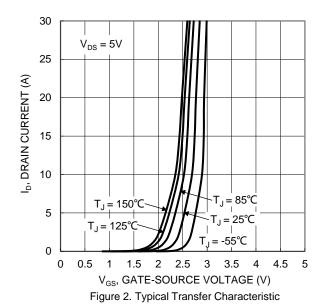
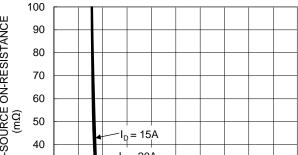


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





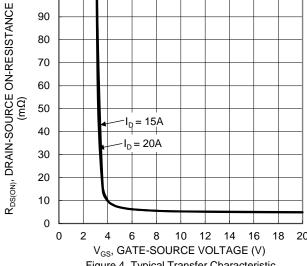


Figure 4. Typical Transfer Characteristic

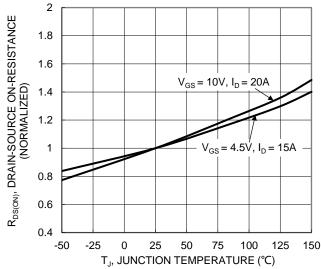


Figure 6. On-Resistance Variation with Temperature



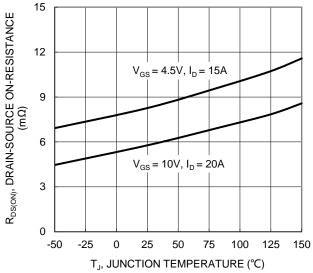


Figure 7. On-Resistance Variation with Temperature

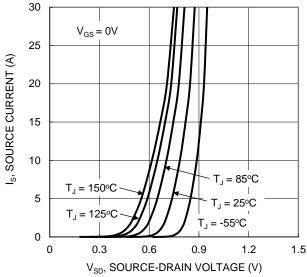
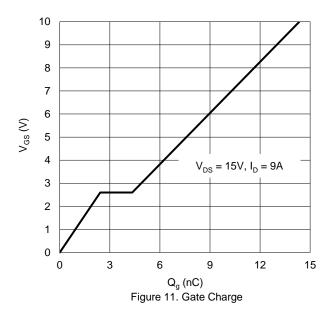


Figure 9. Diode Forward Voltage vs. Current



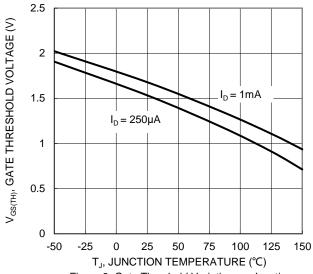
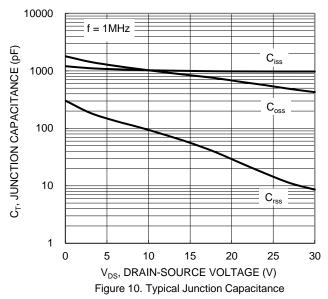


Figure 8. Gate Threshold Variation vs. Junction Temperature



100 10 ID, DRAIN CURRENT (A)  $_{N} = 10 \mu s$ P<sub>W</sub> = 100μs 0.1 = 100mś  $T_{J(Max)} = 150$ °C  $T_{\rm C} = 25^{\circ}{\rm C}$ 0.01 Single Pulse DUT on 1\*MRP Board  $V_{GS} = 10V$ 0.001 0.01 10 100 1 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area

October 2021



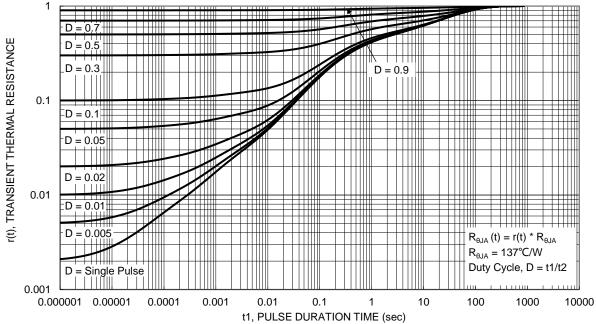


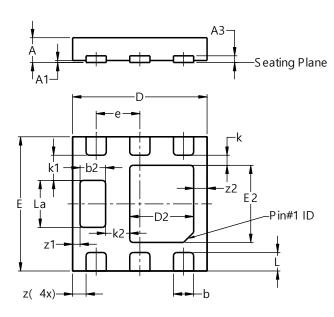
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X2-DFN2020-6 (Type W)

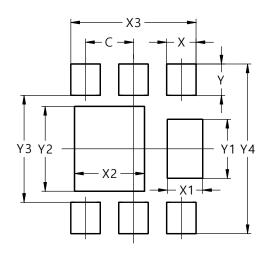


	X2-DFN2020-6 Type W						
Dim							
Α	0.34	0.40	0.37				
A1	0.00	0.05	0.02				
A3			0.100				
b	0.25	0.35	0.30				
b2	0.33	0.43	0.38				
D	1.95	2.05	2.00				
D2	0.85	1.05	0.95				
Е	1.95	2.05	2.00				
E2	1.05	1.25	1.15				
е			0.65				
k							
k1			0.375				
k2			0.36				
L	0.225	0.325	0.275				
La	0.65	0.75	0.70				
Z							
<b>z</b> 1		_	0.11				
z2		_	0.20				
All	Dimensi	ons in n	nm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X2-DFN2020-6 (Type W)



Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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